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Calibration of Electromigration Reliability of Flip-Chip Packages by Electrothermal Coupling Analysis

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In this article, some of the entries in Table I were misplaced. Below please find the correct version of the table.

Table I. Electromigration Fatigue Lives

Cell	I (mA)	\bar{J} (kA/cm ²)	T _{amb} (°C)	N (h)	β
A-1	80	1.26	125	8145	26.4
A-2			150	1012	4.6
A-3			160	434	3.3
B-1	160	2.52	125	4473	11.2
B-2			150	506	9.6
B-3			160	307	8.9
C-1	320	5.03	125	1212	7.5
C-2			150	124	5.73
C-3			160	81	15.9
D	960	15.09	93	1433	1.60
E-1	1280	20.12	59	1493	1.83
E-2			75	568	1.69